

FEATURES

- | 80W Peak Pulse Power per Line (tp=8/20μs)
- | Protects One bidirectional I/O line
- | Working voltages : 3.3 V
- | Low leakage current
- | Low clamping voltage

APPLICATIONS

- | Cell Phone Handsets and Accessories
- | Microprocessor based equipment
- | Personal Digital Assistants (PDA'S)
- | Notebooks,Desktops,and Servers
- | Portable Instrumentation
- | Peripherals
- | I²C Bus Protection



DFN0603



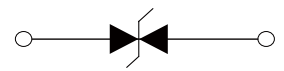
Marking

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003



Schematic Symbol

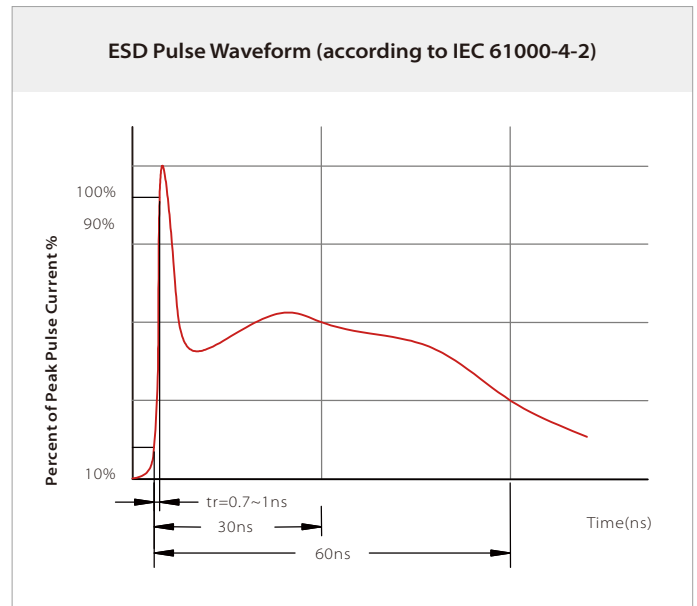
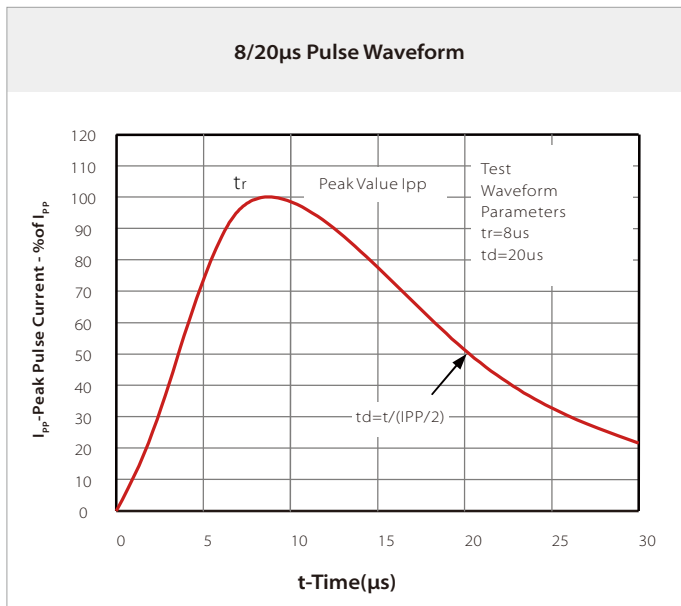
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P _{PP}	Peak Pulse Power (tp=8/20μs waveform)	80	Watts
T _J	Operating Temperature Range	-55 to +125	°C
T _{STG}	Storage Temperature Range	-55 to +125	°C

ELECTRICAL CHARACTERISTICS

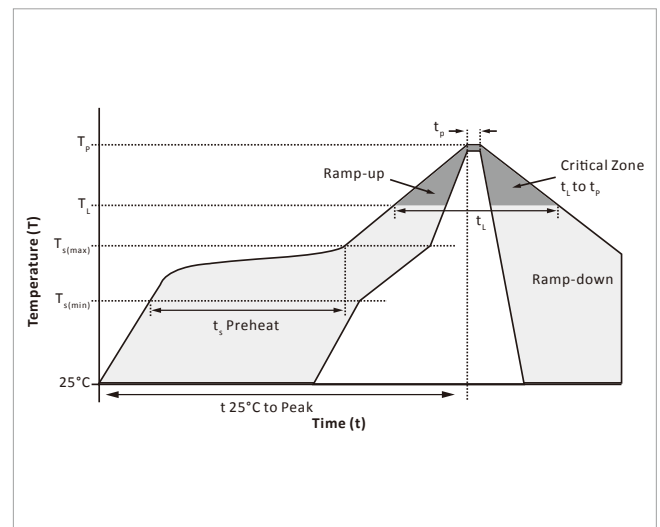
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V _{RWM}	Reverse Stand-off Voltage				3.3	V
V _{BR}	Reverse Breakdown Voltage	I _T =1 mA	4			V
I _R	Reverse Leakage Current	V _{RWM} =3.3V			0.5	μA
V _C	Clamping Voltage (Tp=8/20us)	I _{pp} =1A, tp=8/20us		5		V
V _C	Clamping Voltage (Tp=8/20us)	I _{pp} =10A, tp=8/20us		8		V
I _{pp}	Peak Pulse Current (Tp=8/20us)	tp=8/20us			10	A
C _J	Off State Junction Capacitance	V _R =0V, f=1MHz		18		pF

CHARACTERISTIC CURVES

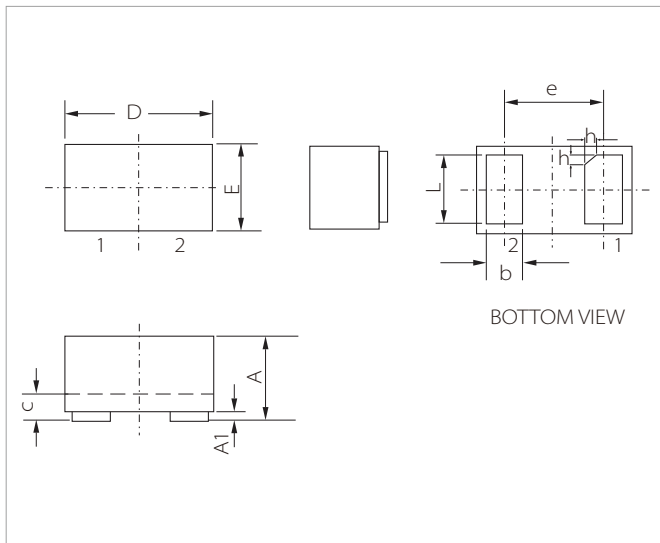


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

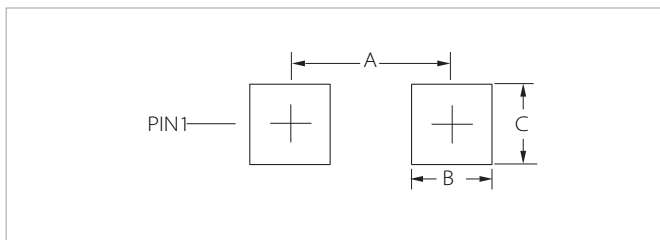


DFN0603 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.28	0.34	0.011	0.014
A1	0	0.05	0	0.002
b	0.13	0.24	0.005	0.009
c	0.05	0.15	0.002	0.006
D	0.55	0.65	0.022	0.026
e	0.35BSC		0.014BSC	
E	0.25	0.35	0.010	0.014
L	0.20	0.30	0.008	0.012
h	0	0.10	0	0.004

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	0.38	0.015
B	0.23	0.009
C	0.30	0.012

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE06F08B3.3A	DFN0603	10000PCS	7"

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